ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC. Bannocki	ourn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration he declaration en	on of the sub compasses	bstances v all lower	vithin the manufactur level materials for w	rer listed it hich the m	em. Note: i anufacture	f the item is an as r has engineering	sembly with low responsibility.
			Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information					
Supplier Information													
Company name* Compa			mpany unique ID			Unique ID Authority				Response Date*			
onsemi										2024-04-25			
Contact Name Title - Contact			ct			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Pro			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	М	Ianufacturing Site	V	Weight*	UOM	Unit Type
	FOD814	D814AS 4PB AC TR SMD)		2024-04-25		L	LITEONFG		224.155	mg	Each
Aanufacturing Proccess Informa	ation							1					
Terminal Plating / Grid Array M	Iaterial 7	Terminal Base Alloy		J-STD-020 MSI	Rating	Peak Proce	ess Body Temperature Max Time at Peak		Temperat	ure Numb	per of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	1			260 C		30	secon	ds 3			
omments													
vel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

sigma range of distribution unless otherwise noted).

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.74	mg	Supplier	Filler (SiO2)	68909-20-6		0.148	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.592	mg
Die	0.099	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.033	mg
			Supplier	Silicon (Si)	7440-21-3		0.066	mg
Die Attach	0.085	mg	Supplier	Silver (Ag)	7440-22-4		0.0697	mg
			Supplier	Dicyandiamine	461-58-5		0.0009	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0145	mg
Lead Frame	55.77	mg	Supplier	Sulfur (S)	7704-34-9		0.0056	mg
			Supplier	Carbon (C)	7440-44-0		0.0558	mg
			Supplier	Manganese (Mn)	7439-96-5		0.1394	mg
			Supplier	Silicon (Si)	7440-21-3		0.0558	mg
			Supplier	Iron (Fe)	7439-89-6		55.5079	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0056	mg
Mold Compound-Black	100.0	mg	В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		2	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.5	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		71	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		17.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		7.5	mg
Mold Compound-White	63.2	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.64	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.24	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		6.32	mg
Plating	4.21	mg	Supplier	Tin (Sn)	7440-31-5		4.21	mg
Wire Bond - Au	0.051	mg	Supplier	Gold (Au)	7440-57-5		0.051	mg